

# SRIDB5050R SERIES

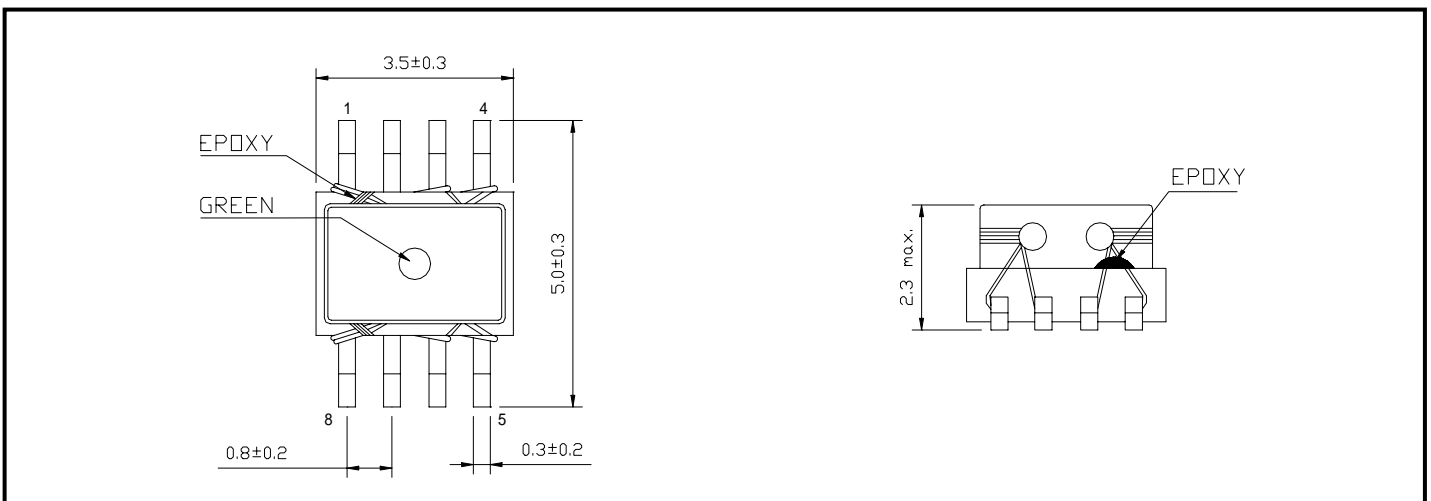


## PART NUMBERING SYSTEM

<b>SRIDB</b>	<b>5 0 5 0</b>	<b>-</b>	<b>9 0 0 R</b>	<b>- LF</b>
TYPE	DIMENSIONS		IMPEDANCE	LEAD FREE

## SHAPES AND DIMENSIONS

UNIT : mm



## SPECIFICATION TABLE

PART NUMBER	RATED CURRENT (mA)	COMMON MODE IMPEDANCE ( )		DCR ( ) max.	WITHSTANDING VOLTAGE (Vdc)	INSULATION RESISTANCE ( ) (min)	OPERATING TEMP. ( )
		100MHz	300MHz				
SRIDB5050-900R-LF	500	90±25%	250 (TYP.)	0.10	100	100 M	-40~+85
SRIDB5050-201R-LF	500	200±25%	300 (TYP.)	0.12	100	100 M	-40~+85
SRIDB5050-301R-LF	500	300±25%	530 (TYP.)	0.15	100	100 M	-40~+85
SRIDB6560-501R-LF	500	500±25%	900 (TYP.)	0.16	100	100 M	-40~+85

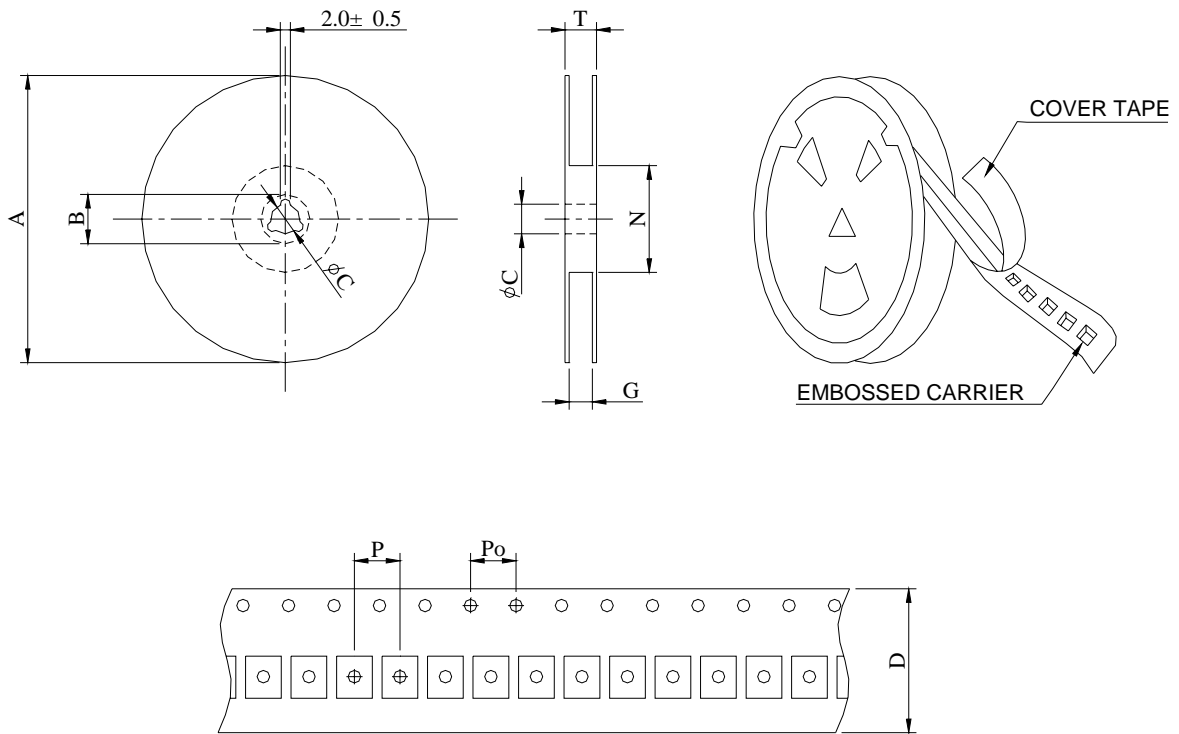
TEST EQUIPMENT : HP-4291A



# SRIDB5050R SERIES



## PACKAGING SPECIFICATION

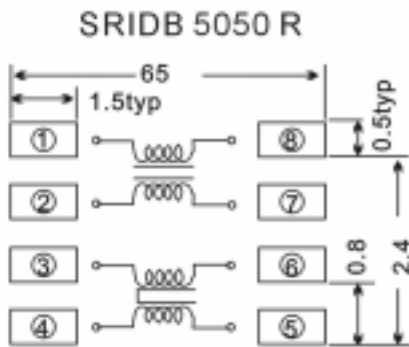


SERIES	STAYLE	Q ' TY (PCS)	DIMENSIONS (m/m)								
			A	B±0.8	C±0.5	D	G <sup>+0</sup>	N <sup>0</sup>	P	Po	T
SRIDB5050R	12	3000	330	21	13	12	12.4	75	8	4	16.4

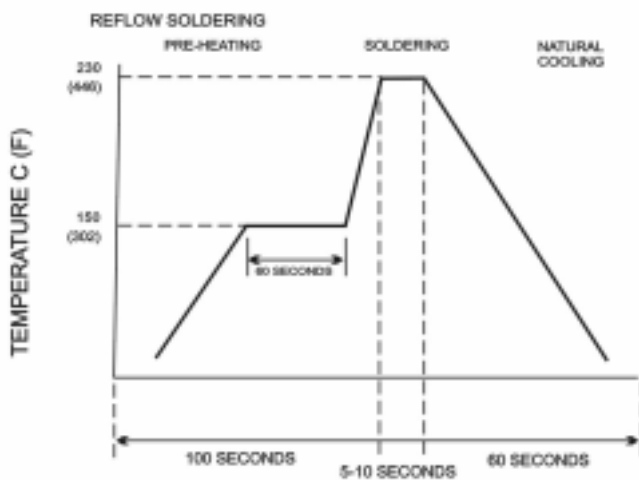
## SRIDB5050R SERIES



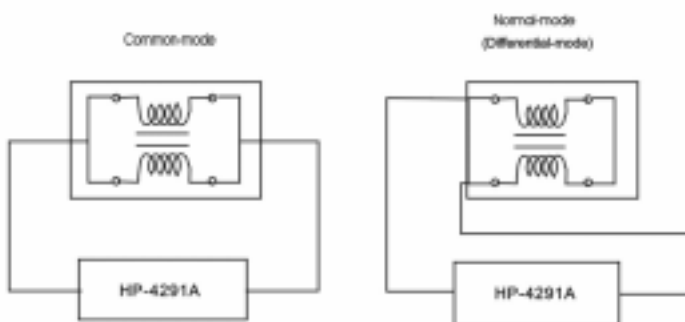
### RECOMMENDED PC BOARD PATTERN (unit:mm)



### RECOMMENDED REFLOW SOLDERING CONDIDIONS



### MEASURING CIRCUIT

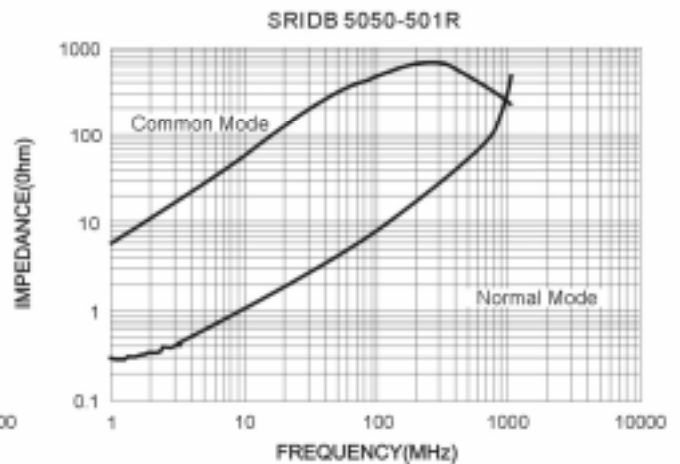
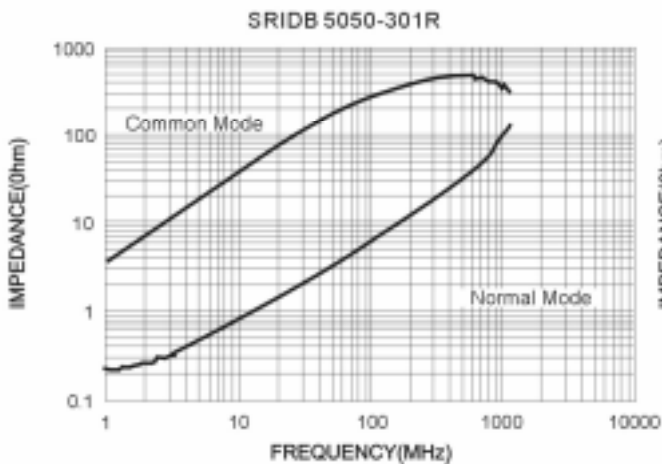
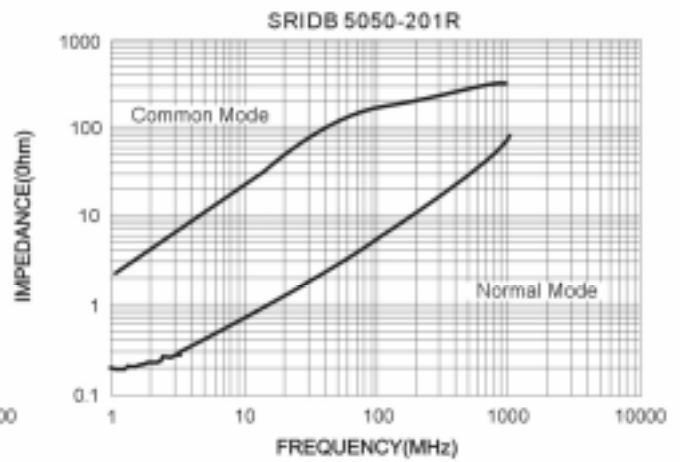
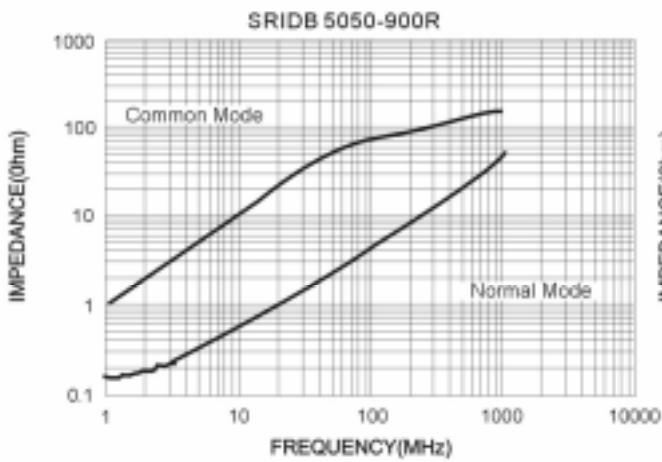


# SRIDB5050R SERIES



## TYPICAL ELECTRICAL CHARACTERISTICS

SRIDB 5050R SERIES COMMON MODE vs. NORMAL MODE CHARACTERISTICS





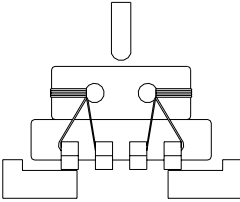


## RELIABILITY TEST

TEST ITEMS	SPECIFICATIONS	TEST CONDITIONS/TEST METHODS
ELECTRICAL PERFORMANCE TEST		
INSERTION LOSS	REFER TO STANDARD ELECTRICAL CHARACTERISTIC LIST	HP-8714C OR EQUIV
IMPEDANCE		HP-4291A OR EQUIV
WITHSTAND VOLTAGE		CH-901 OR EQUIV
TEMPERATURE RISE TEST	40 MAX ( t )	<ol style="list-style-type: none"> <li>APPLIED THE ALLOWED DC CURRENT FOR 4 HOURS.</li> <li>TEMPERATURE MEASURE BY DIGITAL SURFACE THERMOMETER.</li> </ol>
<b><u>MECHANICAL PERFORMANCE TEST</u></b>		
SOLDER HEAT RESISTANCE	<ol style="list-style-type: none"> <li>PRODUCT SHOULD HAVE NO EVIDENCE OF ELECTRICAL AND MICHANICAL DAMAGE.</li> <li>IMPEDANCE SHOULD NOT CHANGE MORE THAN <math>\pm 10\%</math>.</li> </ol>	PREHEAT : 150 60SECS  SOLDER TEMPERATURE : $260\pm 5$ FLUX : ROXIN DIP TIME : $5\pm 2$ SECS <div style="text-align: right;"> </div>
VIBRATION TEST (LOW REQUENCY)		<ol style="list-style-type: none"> <li>AMPLITUDE : 1.5mm</li> <li>FREQUENCY : 10-55-10HZ / 1 MIN</li> <li>DIRECTION : X, Y, Z</li> <li>DURATION : 2 HRS/X, Y, Z</li> </ol>
SHOCK TEST		INDUCTORS SHOULD BE DROPPED 10 TIMES FROM A HEIGHT OF 1m ONTO 3cm WOODEN BOARD.
SOLDERABILITY TEST	MORE THAN 90% OF TERMINDAL ELECTRODE SHOULD BE COVERED WITH SOLDER.	AFTER FLUXING, INDUCTOR SHALL BE DIPPED IN A MELTED SOLDER BATH AT $230\pm 5$ FOR 5 SECONDS. <div style="text-align: right;"> </div>



## RELIABILITY TEST

TEST ITEMS	SPECIFICATIONS	TEST CONDITIONS/TEST METHODS
MECHANICAL PERFORMANCE TEST		
COMPONENT ADHESION ( PUSH TEST )	0.8Kg Min	THE DEVICE SHOULD BE REFLOW SOLDERED ( $232\pm 5$ FOR 10 SECONDS ) TO A TINNED COPPER SUBSTRATE A DYNOMETER FORCE GAUGE SHOULD BE APPLIED TO THE SIDE OF THE COMPONENT THE DEVICE MUST WITH-ST1.0Kg WITHOUT AILURE OF THE TERMINATION ATTACHED TO COMPONENT 
COMPONENT ADHESION ( PULL TEST )	0.75Kg Min	1.INSERT 10cm WIRE INTO THE REMAINING OPEN EYE BEND THE ENDS OF EVEN WIRE LENGTHS UPWARD AND WIND TOGETHER 2.TERMINAL SHALL NOT BE REMARKABLY DAMAGED 
FLEXTURE STRENGTH	THE FORCES APPLIED SHOULD NOT DAMAGE THE DIELECTRIC	SOLDER A CHIP ON A TEST SUBSTRATE, BEND THE SUBSTRATE BY 2mm AND RETURN. 
RESISTANCE TO SOLVENT TEST	THERE SHOULD BE NO CASE DEFORMATION, CHANGE IN APPEARANCE OR BITERATION OF MARKING	PRODUCT SHALL WITHSTAND 6 MINTES OF ALCOHOL



## RELIABILITY TEST

TEST ITEMS	SPECIFICATIONS	TEST CONDITIONS/TEST METHODS
CLIMATIC TEST		
TEMPERATURE CHARACTERISTIC	1. APPEARANCE NO DAMAGE 2. IMPEDANCE : WITHIN±20% OF INITIAL VALUE	-25    +85
HUMIDITY TEST		1. TEMPERATURE : 60 ±2 2. HUMIDITY : 90-95%RH 3. APPLIED CURRENT : MAX RATED CURREN 4. TIME : 96±2 HOURS 5. MEASURE AT ROOM TEMPERATURE AFTER PLACING FOR 24HRS
LOW TEMPERATURE STORAGE		1. TEMPERATURE : -25 ±2 2. TIME : 96±2 HOURS 3. MEASURE AT ROOM TEMPERATURE AFTER PALCING FOR 24 Hrs
THERMAL SHOCK TEST		1. -40 FOR 5 MINUTES CONTINUE 1 HOUR AND 55 MINUTES +85 FOR 5 MINUTES CONTINUE 1 HOUR AND 55 MINUTE 2. TOTAL 4 CYCLES
HIGH TEMPERATURE STORAGE		1. APPLIED CURRENT : MAX RATED CURRENT 2. TEMPERATURE : 85 ±2 3. TIME : 96±2 HOURS 4. MEASURE AT ROOM TEMPERATURE AFTER PLACING FOR 24HRS
NOTE : PRODUCT ARE TO BE TESTED AFTER 4 HOUR AT ROOM TEMPERATURE		
<b><u>LIFE TEST</u></b>		
HIGH TEMPERATURE LOAD LIFE TEST	PRODUCT SHOULD BE NO EVIDENCE OF SHORT OR OPEN CIRCUIT	1. TEMPERATURE : 85±2 2. TIME : 500±12 HOURS 3. LOAD : ALLOWED DC CURRENT
HUMIDITY LOAD LIFE TEST		1. TEMPERATURE : 60±2 2. R.H. : 90-95% 3. TIME : 500±12 HOURS 4. LOAD : ALLOWED DC CURRENT